

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SinJae Lee	10/23/2009
JinGwan Kim	10/23/2009
JiHoon Oh	10/23/2009
KyuWon Lee	10/23/2009
JaeHyun Lim	10/23/2009
RECEIVING PARTY DATA	
Name:	STATS ChipPAC, Ltd.
Street Address:	10 Ang Mo Kio Street 65
Internal Address:	#05-17/20 Techpoint
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	569059
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12605292
CORRESPONDENCE DATA	
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<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	602-748-4408
Email:	main@plgaz.com
Correspondent Name:	Robert D. Atkins
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Address Line 2:	Suite 104
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ATTORNEY DOCKET NUMBER:	2515.0191

CH \$40.00 12605292

NAME OF SUBMITTER:

Robert D. Atkins

Total Attachments: 5

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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, SINJAE LEE of Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING A SHIELDING LAYER OVER A SEMICONDUCTOR DIE DISPOSED IN A CAVITY OF AN INTERCONNECT STRUCTURE AND GROUNDED THROUGH THE DIE TSV, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0191, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.


Signature for SINJAE LEE

Witnessed on this date:

Oct 22, 2009

Signature of Witness:



Printed Name of Witness:

Myoungsu Chae

Address of Witness:

San 136-1, Ami-ri, Dubeal-eub
Icheon-si, Kyongki-do, 467-701, Korea.

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, JINGWAN KIM of Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING A SHIELDING LAYER OVER A SEMICONDUCTOR DIE DISPOSED IN A CAVITY OF AN INTERCONNECT STRUCTURE AND GROUNDED THROUGH THE DIE TSV, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0191, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for JINGWAN KIM

Witnessed on this date:

Oct 23, 2009

Signature of Witness:



Printed Name of Witness:

Han Jeong

Address of Witness:

Sin 130-1, Amn-ri, Bukal-sub
Icheon-si, Kyanggi-do, Korea

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JH OH
Signature for JIHOON OH

Witnessed on this date: 2009 10, 23

Signature of Witness: [Signature]

Printed Name of Witness: Soo-young Lee

Address of Witness: San 136-1 Amni-e Bubal-eup
Icheon-si Kyonggi-do Korea 469991

ASSIGNMENT AND AGREEMENT

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Signature for KYUWON LEE

Witnessed on this date: 2009-10-23

Signature of Witness: 

Printed Name of Witness: Sunyoung Chun

Address of Witness: 514, Songjuk-dong, Jangam-gu, Suwon-si, Gyeonggi-do, Korea

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, JAEHYUN LIM of Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING A SHIELDING LAYER OVER A SEMICONDUCTOR DIE DISPOSED IN A CAVITY OF AN INTERCONNECT STRUCTURE AND GROUNDED THROUGH THE DIE TSV, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0191, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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JH Lim

Signature for JAEHYUN LIM

Witnessed on this date:

2009.10.23

Signature of Witness:

[Signature]

Printed Name of Witness:

Young Deuk Lee

Address of Witness:

Sen 126-1 Ami-n Bubal-eup

Ichon-si Kyonggi-do Korea 460901

PATENT